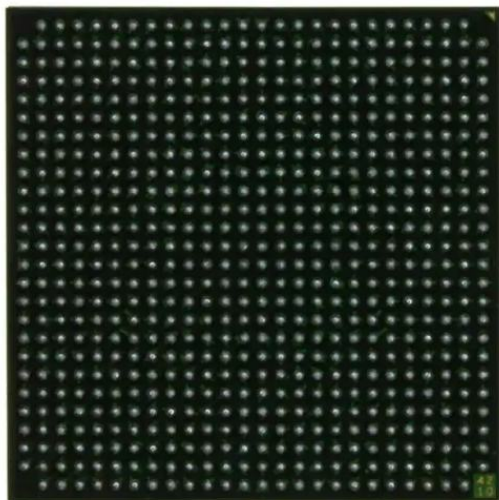




Welcome to [E-XFL.COM](https://www.e-xfl.com)

Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	752
Number of Logic Elements/Cells	6768
Total RAM Bits	516096
Number of I/O	348
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA, FCBGA
Supplier Device Package	672-FCBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp4-5ffg672c

- Programmable Receiver Equalization
- Internal AC Coupling
- On-Chip 50Ω Termination
 - Eliminates the need for external termination resistors
- Pre- and Post-Driver Serial and Parallel TX-to-RX
- Internal Loopback Modes for Testing Operability
- Programmable Comma Detection
 - Allows for any protocol
 - Allows for detection of any 10-bit character
- 8B/10B and 64B/66B Encoding Blocks

RocketIO Transceiver Features (All Except XC2VPX20 and XC2VPX70)

- Full-Duplex Serial Transceiver (SERDES) Capable of Baud Rates from 600 Mb/s to 3.125 Gb/s
- 100 Gb/s Duplex Data Rate (20 Channels)
- Monolithic Clock Synthesis and Clock Recovery (CDR)
- Fibre Channel, 10G Fibre Channel, Gigabit Ethernet, 10 Gb Attachment Unit Interface (XAUI), and Infiniband-Compliant Transceivers
- 8-, 16-, or 32-bit Selectable Internal FPGA Interface
- 8B/10B Encoder and Decoder (optional)
- 50Ω / 75Ω on-chip Selectable Transmit and Receive Terminations
- Programmable Comma Detection
- Channel Bonding Support (from 2 to 20 Channels)
- Rate Matching via Insertion/Deletion Characters
- Four Levels of Selectable Pre-Emphasis
- Five Levels of Output Differential Voltage
- Per-Channel Internal Loopback Modes
- 2.5V Transceiver Supply Voltage

PowerPC RISC Processor Block Features (All Except XC2VP2)

- Embedded 300+ MHz Harvard Architecture Block
- Low Power Consumption: 0.9 mW/MHz
- Five-Stage Data Path Pipeline
- Hardware Multiply/Divide Unit
- Thirty-Two 32-bit General Purpose Registers
- 16 KB Two-Way Set-Associative Instruction Cache
- 16 KB Two-Way Set-Associative Data Cache
- Memory Management Unit (MMU)
 - 64-entry unified Translation Look-aside Buffers (TLB)
 - Variable page sizes (1 KB to 16 MB)
- Dedicated On-Chip Memory (OCM) Interface
- Supports IBM CoreConnect™ Bus Architecture
- Debug and Trace Support
- Timer Facilities

Virtex-II Pro Platform FPGA Technology (All Devices)

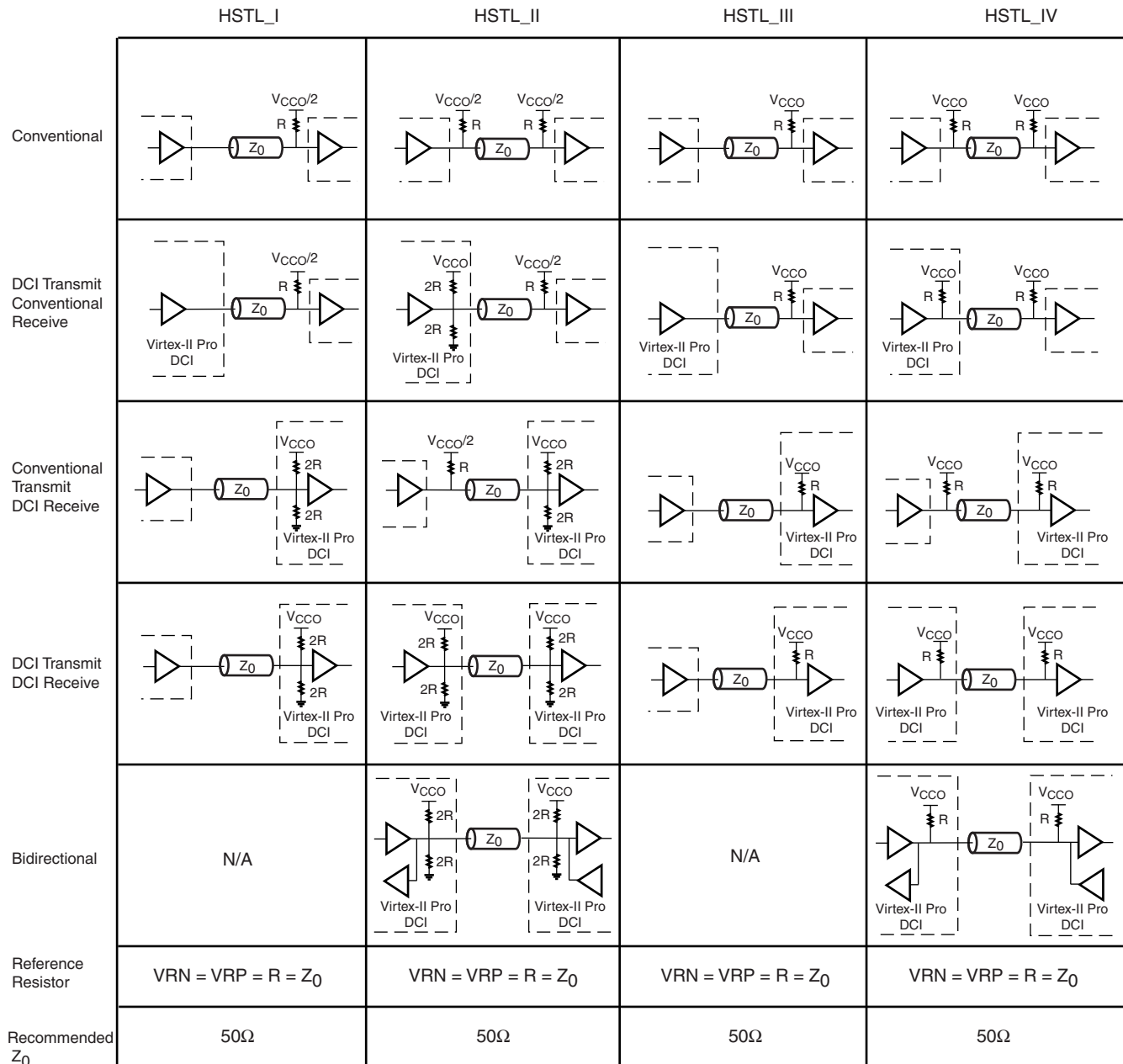
- SelectRAM+ Memory Hierarchy
 - Up to 8 Mb of True Dual-Port RAM in 18 Kb block SelectRAM+ resources
 - Up to 1,378 Kb of distributed SelectRAM+ resources
 - High-performance interfaces to external memory
- Arithmetic Functions
 - Dedicated 18-bit x 18-bit multiplier blocks
 - Fast look-ahead carry logic chains
- Flexible Logic Resources
 - Up to 88,192 internal registers/latches with Clock Enable
 - Up to 88,192 look-up tables (LUTs) or cascadable variable (1 to 16 bits) shift registers
 - Wide multiplexers and wide-input function support
 - Horizontal cascade chain and Sum-of-Products support
 - Internal 3-state busing
- High-Performance Clock Management Circuitry
 - Up to twelve Digital Clock Manager (DCM) modules
 - Precise clock de-skew
 - Flexible frequency synthesis
 - High-resolution phase shifting
 - 16 global clock multiplexer buffers in all parts
- Active Interconnect Technology
 - Fourth-generation segmented routing structure
 - Fast, predictable routing delay, independent of fanout
 - Deep sub-micron noise immunity benefits
- SelectIO™-Ultra Technology
 - Up to 1,164 user I/Os
 - Twenty-two single-ended standards and ten differential standards
 - Programmable LVCMOS sink/source current (2 mA to 24 mA) per I/O
 - XCITE Digitally Controlled Impedance (DCI) I/O
 - PCI/PCI-X support ⁽¹⁾
 - Differential signaling
 - 840 Mb/s Low-Voltage Differential Signaling I/O (LVDS) with current mode drivers
 - On-chip differential termination
 - Bus LVDS I/O

1. Refer to [XAPP653](#) for more information.

Table 15: SelectIO-Ultra Differential Buffers With On-Chip Termination

I/O Standard Description	IOSTANDARD Attribute	
	External Termination	On-Chip Termination
LVDS 2.5V	LVDS_25	LVDS_25_DCI
LVDS Extended 2.5V	LVDSEXT_25	LVDSEXT_25_DCI

Figure 28 provides examples illustrating the use of the HSTL_I_DCI, HSTL_II_DCI, HSTL_III_DCI, and HSTL_IV_DCI I/O standards. For a complete list, see the [Virtex-II Pro Platform FPGA User Guide](#).



DS083-2_65a_082102

Figure 28: HSTL DCI Usage Examples

Figure 36, Figure 37, and Figure 38 illustrate various example configurations.

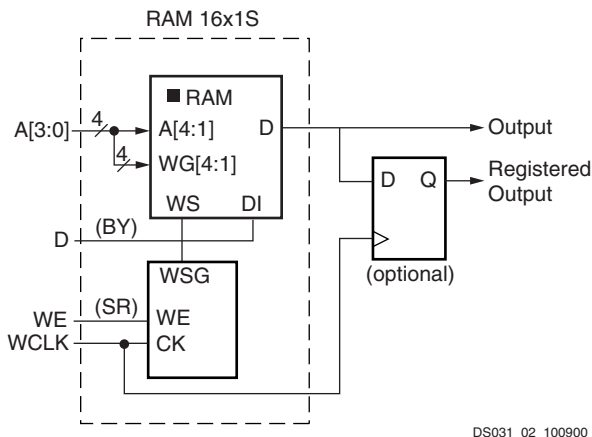


Figure 36: Distributed SelectRAM+ (RAM16x1S)

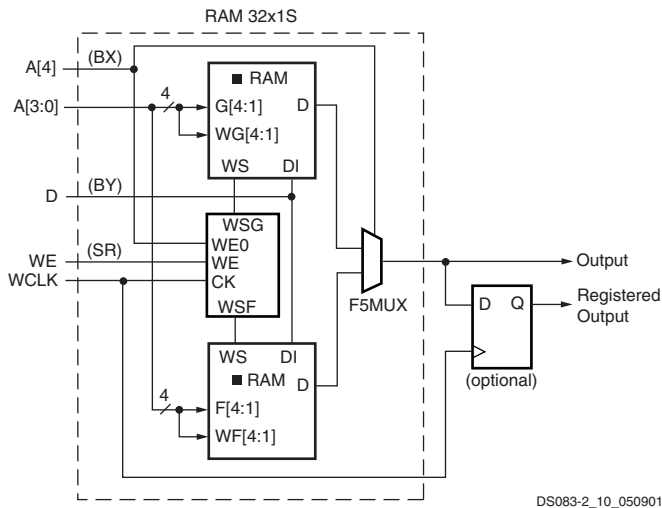


Figure 37: Single-Port Distributed SelectRAM+ (RAM32x1S)

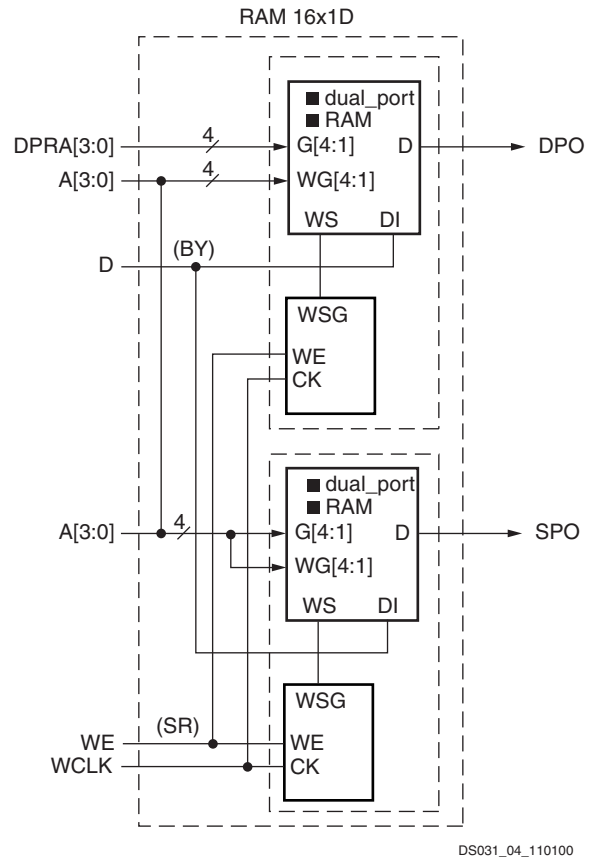


Figure 38: Dual-Port Distributed SelectRAM+ (RAM16x1D)

Similar to the RAM configuration, each function generator (LUT) can implement a 16 x 1-bit ROM. Five configurations are available: ROM16x1, ROM32x1, ROM64x1, ROM128x1, and ROM256x1. The ROM elements are cascadable to implement wider or/and deeper ROM. ROM contents are loaded at configuration. Table 17 shows the number of LUTs occupied by each configuration.

Table 17: ROM Configuration

ROM	Number of LUTs
16 x 1	1
32 x 1	2
64 x 1	4
128 x 1	8 (1 CLB)
256 x 1	16 (2 CLBs)

Table 40: Output Delay Measurement Methodology

Description	IOSTANDARD Attribute	R _{REF} (Ω)	C _{REF} ⁽¹⁾ (pF)	V _{MEAS} (V)	V _{REF} (V)
SSTL (Stub Series Terminated Logic), Class I, 1.8V	SSTL18_I	50	0	V _{REF}	0.9
SSTL, Class II, 1.8V	SSTL18_II	25	0	V _{REF}	0.9
SSTL, Class I, 2.5V	SSTL2_I	50	0	V _{REF}	1.25
SSTL, Class II, 2.5V	SSTL2_II	25	0	V _{REF}	1.25
LVDS (Low-Voltage Differential Signaling), 2.5V	LVDS_25	50	0	V _{REF}	1.2
LVDS (Low-Voltage Differential Signaling), 2.5V	LVDS_25	50	0	V _{REF}	1.2
BLVDS (Bus LVDS), 2.5V	BLVDS_25	1M	0	1.2	0
LDT (HyperTransport), 2.5V	LDT_25	50	0	V _{REF}	0.6
LVPECL (Low-Voltage Positive Emitter-Coupled Logic), 2.5V	LVPECL_25	1M	0	1.23	0
LVDCI/HSLVDCI (Low-Voltage Digitally Controlled Impedance), 3.3V	LVDCI_33	1M	0	1.65	0
LVDCI/HSLVDCI, 2.5V	LVDCI_25	1M	0	1.25	0
LVDCI/HSLVDCI, 1.8V	LVDCI_18	1M	0	0.9	0
LVDCI/HSLVDCI, 1.5V	LVDCI_15	1M	0	0.75	0
HSTL (High-Speed Transceiver Logic), Class I & II, with DCI	HSTL_I_DCI, HSTL_II_DCI	50	0	V _{REF}	0.75
HSTL, Class III & IV, with DCI	HSTL_III_DCI, HSTL_IV_DCI	50	0	0.9	1.5
HSTL, Class I & II, 1.8V, with DCI	HSTL_I_DCI_18, HSTL_II_DCI_18	50	0	V _{REF}	0.9
HSTL, Class III & IV, 1.8V, with DCI	HSTL_III_DCI_18, HSTL_IV_DCI_18	50	0	1.1	1.8
SSTL (Stub Series Termini.Logic), Class I & II, 1.8V, with DCI	SSTL18_I_DCI, SSTL18_II_DCI	50	0	V _{REF}	0.9
SSTL, Class I & II, 2.5V, with DCI	SSTL2_I_DCI, SSTL2_II_DCI	50	0	V _{REF}	1.25
GTL (Gunning Transceiver Logic) with DCI	GTL_DCI	50	0	0.8	1.2
GTL Plus with DCI	GTLP_DCI	50	0	1.0	1.5

Notes:

1. C_{REF} is the capacitance of the probe, nominally 0 pF.
2. Measured as per PCI specification.
3. Measured as per PCI-X specification.



Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Pinout Information

DS083 (v5.0) June 21, 2011

Product Specification

This document provides Virtex™-II Pro Device/Package Combinations, Maximum I/Os, and Virtex-II Pro Pin Definitions, followed by pinout tables, for these packages:

- FG256/FGG256 Fine-Pitch BGA Package
- FG456/FGG456 Fine-Pitch BGA Package
- FG676/FGG676 Fine-Pitch BGA Package
- FF672 Flip-Chip Fine-Pitch BGA Package
- FF896 Flip-Chip Fine-Pitch BGA Package

- FF1152 Flip-Chip Fine-Pitch BGA Package
- FF1148 Flip-Chip Fine-Pitch BGA Package
- FF1517 Flip-Chip Fine-Pitch BGA Package
- FF1704 Flip-Chip Fine-Pitch BGA Package
- FF1696 Flip-Chip Fine-Pitch BGA Package

For device pinout diagrams and layout guidelines, refer to the [Virtex-II Pro Platform FPGA User Guide](#). ASCII package pinout files are also available for download from the Xilinx website (www.xilinx.com).

Virtex-II Pro Device/Package Combinations and Maximum I/Os⁽¹⁾

Wire-bond and flip-chip packages are available. [Table 1](#) and [Table 2](#) show the maximum number of user I/Os possible in wire-bond and flip-chip packages, respectively.

- FG denotes wire-bond fine-pitch BGA (1.00 mm pitch).
- FGG denotes Pb-free wire-bond fine-pitch BGA (1.00 mm pitch).
- FF denotes flip-chip fine-pitch BGA (1.00 mm pitch)

Table 1: Wire-Bond Packages Information

Package ⁽¹⁾	FG256/ FGG256	FG456/ FGG456	FG676/ FGG676
Pitch (mm)	1.00	1.00	1.00
Size (mm)	17 x 17	23 x 23	26 x 26
Maximum I/Os	140	248	412

Notes:

1. Wire-bond packages include FGGnnn Pb-free versions. See [Virtex-II Pro Ordering Examples \(Module 1\)](#).

Table 2: Flip-Chip Packages Information

Package	FF672	FF896	FF1152	FF1148	FF1517	FF1704	FF1696
Pitch (mm)	1.00	1.00	1.00	1.00	1.00	1.00	1.00
Size (mm)	27 x 27	31 x 31	35 x 35	35 x 35	40 x 40	42.5 x 42.5	42.5 x 42.5
Maximum I/Os	396	556	644	812	964	1040	1200

[Table 3](#) shows the number of available I/Os, the number of RocketIO™ (or RocketIO X) multi-gigabit transceiver (MGT) pins, and the number of differential I/O pairs for each Virtex-II Pro device/package combination. The number of I/Os per package includes all user I/Os *except* the fifteen control pins (CCLK, DONE, M0, M1, M2, PROG_B, PWRDWN_B, TCK, TDI, TDO, TMS, HSWAP_EN, DXN, DXP, and RSVD), the nine (per transceiver) RocketIO MGT pins (TXP, TXN, RXP, RXN, AVCCAUTX, AVCCAUXRX, VTTX, VTRX, and GNDA), and for Virtex-II Pro X devices only, the two BREFCLKN/BREFCLKP differential clock input pairs (four pins). The Virtex-II Pro X devices are highlighted in bold type.

1. Unless otherwise noted, "Virtex-II Pro" refers to members of the Virtex-II Pro and/or Virtex-II Pro X families.

Table 5: FG256/FGG256 — XC2VP2 and XC2VP4

Bank	Pin Description	Pin Number
5	IO_L06N_5/VRP_5	P5
5	IO_L06P_5/VRN_5	N5
5	IO_L03N_5/D4	T3
5	IO_L03P_5/D5	T2
5	IO_L02N_5/D6	P4
5	IO_L02P_5/D7	R3
5	IO_L01N_5/RDWR_B	P3
5	IO_L01P_5/CS_B	P2
6	IO_L01P_6/VRN_6	M3
6	IO_L01N_6/VRP_6	M2
6	IO_L02P_6	N1
6	IO_L02N_6	M1
6	IO_L03P_6	M4
6	IO_L03N_6/VREF_6	L5
6	IO_L05P_6	L4
6	IO_L05N_6	L3
6	IO_L06P_6	L2
6	IO_L06N_6	L1
6	IO_L85P_6	K4
6	IO_L85N_6	K3
6	IO_L87P_6	K2
6	IO_L87N_6/VREF_6	K1
6	IO_L89P_6	K5
6	IO_L89N_6	J4
6	IO_L90P_6	J3
6	IO_L90N_6	J2
7	IO_L90P_7	J1
7	IO_L90N_7	H1
7	IO_L88P_7	H2
7	IO_L88N_7/VREF_7	H3
7	IO_L86P_7	H4
7	IO_L86N_7	G5
7	IO_L85P_7	G1

Table 7: FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
2	IO_L31P_2	F26			
2	IO_L32N_2	G22			
2	IO_L32P_2	H22			
2	IO_L34N_2/VREF_2	G23			
2	IO_L34P_2	G24			
2	IO_L36N_2	G25			
2	IO_L36P_2	G26			
2	IO_L37N_2	H20			
2	IO_L37P_2	H21			
2	IO_L38N_2	H25			
2	IO_L38P_2	H26			
2	IO_L40N_2/VREF_2	J19			
2	IO_L40P_2	J20			
2	IO_L42N_2	J21			
2	IO_L42P_2	J22			
2	IO_L43N_2	J23			
2	IO_L43P_2	J24			
2	IO_L44N_2	J25			
2	IO_L44P_2	J26			
2	IO_L46N_2/VREF_2	K19			
2	IO_L46P_2	L19			
2	IO_L48N_2	K22			
2	IO_L48P_2	K23			
2	IO_L49N_2	K24			
2	IO_L49P_2	L24			
2	IO_L50N_2	K25			
2	IO_L50P_2	K26			
2	IO_L52N_2/VREF_2	L20			
2	IO_L52P_2	M20			
2	IO_L54N_2	L21			
2	IO_L54P_2	L22			
2	IO_L55N_2	L25			
2	IO_L55P_2	L26			
2	IO_L56N_2	M18			
2	IO_L56P_2	M19			

Table 7: FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
6	IO_L23N_6	Y6	NC		
6	IO_L24P_6	AA4	NC		
6	IO_L24N_6	AA3	NC		
6	IO_L31P_6	AA2			
6	IO_L31N_6	AA1			
6	IO_L33P_6	Y5			
6	IO_L33N_6/VREF_6	W5			
6	IO_L35P_6	Y4			
6	IO_L35N_6	Y3			
6	IO_L36P_6	Y2			
6	IO_L36N_6	Y1			
6	IO_L37P_6	W7			
6	IO_L37N_6	W6			
6	IO_L39P_6	W2			
6	IO_L39N_6/VREF_6	W1			
6	IO_L41P_6	V8			
6	IO_L41N_6	V7			
6	IO_L42P_6	V6			
6	IO_L42N_6	V5			
6	IO_L43P_6	V4			
6	IO_L43N_6	V3			
6	IO_L45P_6	V2			
6	IO_L45N_6/VREF_6	V1			
6	IO_L47P_6	U8			
6	IO_L47N_6	T8			
6	IO_L48P_6	U5			
6	IO_L48N_6	U4			
6	IO_L49P_6	U3			
6	IO_L49N_6	T3			
6	IO_L51P_6	U2			
6	IO_L51N_6/VREF_6	U1			
6	IO_L53P_6	T7			
6	IO_L53N_6	R7			
6	IO_L54P_6	T6			
6	IO_L54N_6	T5			

Table 8: FF672 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
1	IO_L06N_1	E9			
1	IO_L06P_1	E8			
1	IO_L05_1/No_Pair	F8			
1	IO_L03N_1/VREF_1	D7			
1	IO_L03P_1	E7			
1	IO_L02N_1	C6			
1	IO_L02P_1	D6			
1	IO_L01N_1/VRP_1	A3			
1	IO_L01P_1/VRN_1	B3			
2	IO_L01N_2/VRP_2	C4			
2	IO_L01P_2/VRN_2	D3			
2	IO_L02N_2	A2			
2	IO_L02P_2	B1			
2	IO_L03N_2	C2			
2	IO_L03P_2	C1			
2	IO_L04N_2/VREF_2	D2			
2	IO_L04P_2	D1			
2	IO_L05N_2	E4			
2	IO_L05P_2	E3			
2	IO_L06N_2	E2			
2	IO_L06P_2	E1			
2	IO_L40N_2/VREF_2	F5	NC	NC	NC
2	IO_L40P_2	F4	NC	NC	NC
2	IO_L42N_2	F3	NC	NC	NC
2	IO_L42P_2	F2	NC	NC	NC
2	IO_L43N_2	G6	NC		
2	IO_L43P_2	G5	NC		
2	IO_L44N_2	G4	NC		
2	IO_L44P_2	G3	NC		
2	IO_L45N_2	F1	NC		
2	IO_L45P_2	G1	NC		
2	IO_L46N_2/VREF_2	H6	NC		
2	IO_L46P_2	H5	NC		
2	IO_L47N_2	H4	NC		
2	IO_L47P_2	H3	NC		
2	IO_L48N_2	H2	NC		

Table 9: FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
N/A	GND		U18			
N/A	GND		U17			
N/A	GND		U16			
N/A	GND		U15			
N/A	GND		U14			
N/A	GND		U13			
N/A	GND		U12			
N/A	GND		U6			
N/A	GND		T19			
N/A	GND		T18			
N/A	GND		T17			
N/A	GND		T16			
N/A	GND		T15			
N/A	GND		T14			
N/A	GND		T13			
N/A	GND		T12			
N/A	GND		R19			
N/A	GND		R18			
N/A	GND		R17			
N/A	GND		R16			
N/A	GND		R15			
N/A	GND		R14			
N/A	GND		R13			
N/A	GND		R12			
N/A	GND		P25			
N/A	GND		P19			
N/A	GND		P18			
N/A	GND		P17			
N/A	GND		P16			
N/A	GND		P15			
N/A	GND		P14			
N/A	GND		P13			
N/A	GND		P12			
N/A	GND		P6			
N/A	GND		N19			
N/A	GND		N18			

FF896 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch)

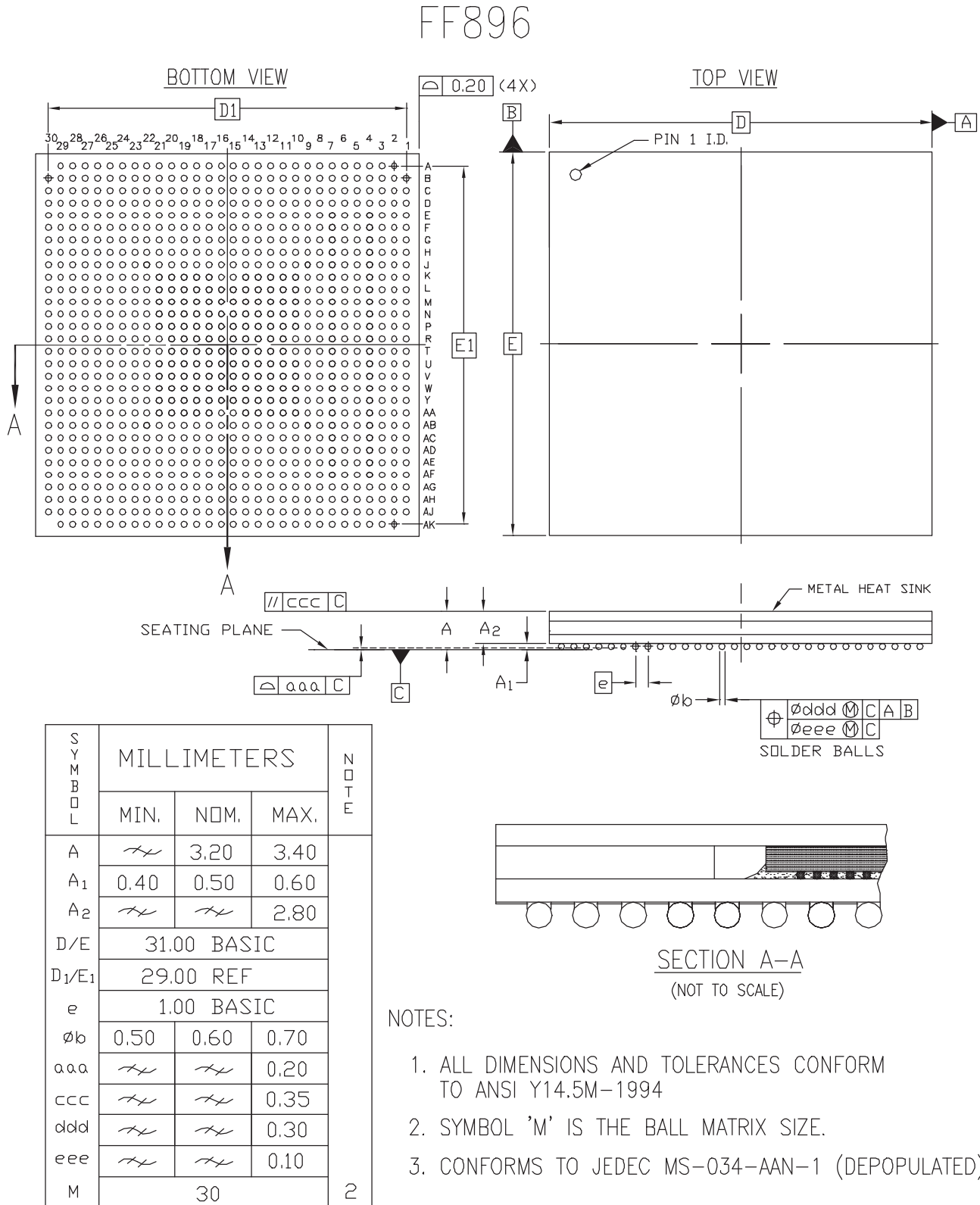


Figure 5: FF896 Flip-Chip Fine-Pitch BGA Package Specifications

Table 10: FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
4	IO_L73P_4	AG17				
4	IO_L74N_4/GCLK3S	AH17				
4	IO_L74P_4/GCLK2P	AJ17				
4	IO_L75N_4/GCLK1S	AK17				
4	IO_L75P_4/GCLK0P	AL17				
5	IO_L75N_5/GCLK7S	AL18				
5	IO_L75P_5/GCLK6P	AK18				
5	IO_L74N_5/GCLK5S	AJ18				
5	IO_L74P_5/GCLK4P	AH18				
5	IO_L73N_5	AG18				
5	IO_L73P_5	AF18				
5	IO_L69N_5/VREF_5	AL19				
5	IO_L69P_5	AK19				
5	IO_L68N_5	AJ19				
5	IO_L68P_5	AH19				
5	IO_L67N_5	AE18				
5	IO_L67P_5	AD18				
5	IO_L57N_5/VREF_5	AL20				
5	IO_L57P_5	AL21				
5	IO_L56N_5	AJ20				
5	IO_L56P_5	AH20				
5	IO_L55N_5	AG19				
5	IO_L55P_5	AF19				
5	IO_L54N_5	AM22				
5	IO_L54P_5	AM21				
5	IO_L53_5/No_Pair	AK21				
5	IO_L50_5/No_Pair	AJ21				
5	IO_L49N_5	AE19				
5	IO_L49P_5	AD19				
5	IO_L48N_5	AL23				
5	IO_L48P_5	AL22				
5	IO_L47N_5	AH21				
5	IO_L47P_5	AG21				
5	IO_L46N_5	AF20				
5	IO_L46P_5	AE20				
5	IO_L45N_5/VREF_5	AM24				
5	IO_L45P_5	AL24				

FF1148 Flip-Chip Fine-Pitch BGA Package

As shown in [Table 11](#), XC2VP40 and XC2VP50 Virtex-II Pro devices are available in the FF1148 flip-chip fine-pitch BGA package. Pins in each of these devices are the same, except for the differences shown in the No Connect column. Following this table are the [FF1148 Flip-Chip Fine-Pitch BGA Package Specifications \(1.00mm pitch\)](#).

Table 11: FF1148 — XC2VP40 and XC2VP50

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
0	IO_L01N_0/VRP_0	E25		
0	IO_L01P_0/VRN_0	F25		
0	IO_L02N_0	J24		
0	IO_L02P_0	K24		
0	IO_L03N_0	C25		
0	IO_L03P_0/VREF_0	D25		
0	IO_L05_0/No_Pair	G25		
0	IO_L06N_0	A25		
0	IO_L06P_0	B25		
0	IO_L07N_0	G24		
0	IO_L07P_0	G23		
0	IO_L08N_0	H23		
0	IO_L08P_0	H22		
0	IO_L09N_0	E24		
0	IO_L09P_0/VREF_0	F24		
0	IO_L19N_0	C24		
0	IO_L19P_0	C23		
0	IO_L20N_0	J23		
0	IO_L20P_0	K23		
0	IO_L21N_0	A24		
0	IO_L21P_0	B24		
0	IO_L25N_0	E23		
0	IO_L25P_0	F23		
0	IO_L26N_0	K22		
0	IO_L26P_0	L22		
0	IO_L27N_0	D23		
0	IO_L27P_0/VREF_0	D22		
0	IO_L37N_0	A23		
0	IO_L37P_0	B23		
0	IO_L38N_0	J21		
0	IO_L38P_0	J20		
0	IO_L39N_0	F22		
0	IO_L39P_0	G22		

Table 11: FF1148 — XC2VP40 and XC2VP50

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
1	IO_L75N_1/GCLK3P	C17		
1	IO_L75P_1/GCLK2S	B17		
1	IO_L74N_1/GCLK1P	L17		
1	IO_L74P_1/GCLK0S	K17		
1	IO_L73N_1	E17		
1	IO_L73P_1	D17		
1	IO_L69N_1/VREF_1	G17		
1	IO_L69P_1	F17		
1	IO_L68N_1	J17		
1	IO_L68P_1	H17		
1	IO_L67N_1	C16		
1	IO_L67P_1	B16		
1	IO_L66N_1/VREF_1	G16	NC	
1	IO_L66P_1	F16	NC	
1	IO_L57N_1/VREF_1	B15		
1	IO_L57P_1	A15		
1	IO_L56N_1	L16		
1	IO_L56P_1	K16		
1	IO_L55N_1	D16		
1	IO_L55P_1	C15		
1	IO_L54N_1	F15		
1	IO_L54P_1	E15		
1	IO_L53_1/No_Pair	H16		
1	IO_L50_1/No_Pair	G15		
1	IO_L49N_1	B14		
1	IO_L49P_1	A14		
1	IO_L48N_1	D14		
1	IO_L48P_1	C14		
1	IO_L47N_1	L15		
1	IO_L47P_1	K15		
1	IO_L46N_1	F14		
1	IO_L46P_1	E14		
1	IO_L45N_1/VREF_1	H14		
1	IO_L45P_1	G14		
1	IO_L44N_1	L14		
1	IO_L44P_1	K14		
1	IO_L43N_1	C13		

Table 11: FF1148 — XC2VP40 and XC2VP50

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
5	IO_L69P_5	AJ18		
5	IO_L68N_5	AF18		
5	IO_L68P_5	AG18		
5	IO_L67N_5	AM19		
5	IO_L67P_5	AN19		
5	IO_L66N_5/VREF_5	AH19	NC	
5	IO_L66P_5	AJ19	NC	
5	IO_L57N_5/VREF_5	AN20		
5	IO_L57P_5	AP20		
5	IO_L56N_5	AD19		
5	IO_L56P_5	AE19		
5	IO_L55N_5	AL19		
5	IO_L55P_5	AM20		
5	IO_L54N_5	AJ20		
5	IO_L54P_5	AK20		
5	IO_L53_5/No_Pair	AG19		
5	IO_L50_5/No_Pair	AH20		
5	IO_L49N_5	AN21		
5	IO_L49P_5	AP21		
5	IO_L48N_5	AL21		
5	IO_L48P_5	AM21		
5	IO_L47N_5	AD20		
5	IO_L47P_5	AE20		
5	IO_L46N_5	AJ21		
5	IO_L46P_5	AK21		
5	IO_L45N_5/VREF_5	AG21		
5	IO_L45P_5	AH21		
5	IO_L44N_5	AD21		
5	IO_L44P_5	AE21		
5	IO_L43N_5	AM22		
5	IO_L43P_5	AN22		
5	IO_L39N_5	AH22		
5	IO_L39P_5	AJ22		
5	IO_L38N_5	AF20		
5	IO_L38P_5	AF21		
5	IO_L37N_5	AN23		
5	IO_L37P_5	AP23		
5	IO_L27N_5/VREF_5	AL22		

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
0	IO_L34P_0	E27	NC	
0	IO_L35N_0	L26	NC	
0	IO_L35P_0	L25	NC	
0	IO_L36N_0	G26	NC	
0	IO_L36P_0/VREF_0	H26	NC	
0	IO_L37N_0	E26		
0	IO_L37P_0	F26		
0	IO_L38N_0	K25		
0	IO_L38P_0	K24		
0	IO_L39N_0	C26		
0	IO_L39P_0	D26		
0	IO_L43N_0	H25		
0	IO_L43P_0	J25		
0	IO_L44N_0	M25		
0	IO_L44P_0	M24		
0	IO_L45N_0	F25		
0	IO_L45P_0/VREF_0	G25		
0	IO_L46N_0	C25		
0	IO_L46P_0	D25		
0	IO_L47N_0	L23		
0	IO_L47P_0	M22		
0	IO_L48N_0	H24		
0	IO_L48P_0	J24		
0	IO_L49N_0	E25		
0	IO_L49P_0	E24		
0	IO_L50_0/No_Pair	N23		
0	IO_L53_0/No_Pair	M23		
0	IO_L54N_0	H23		
0	IO_L54P_0	J23		
0	IO_L55N_0	F24		
0	IO_L55P_0	G23		
0	IO_L56N_0	K22		
0	IO_L56P_0	L22		
0	IO_L57N_0	C23		
0	IO_L57P_0/VREF_0	D23		
0	IO_L58N_0	H22		
0	IO_L58P_0	J22		
0	IO_L59N_0	N22		

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
5	IO_L29N_5	AK26	NC	
5	IO_L29P_5	AL26	NC	
5	IO_L28N_5	AL27	NC	
5	IO_L28P_5	AM27	NC	
5	IO_L27N_5/VREF_5	AR28		
5	IO_L27P_5	AT28		
5	IO_L26N_5	AH26		
5	IO_L26P_5	AH27		
5	IO_L25N_5	AL28		
5	IO_L25P_5	AM28		
5	IO_L21N_5	AT29		
5	IO_L21P_5	AU29		
5	IO_L20N_5	AJ27		
5	IO_L20P_5	AJ28		
5	IO_L19N_5	AP29		
5	IO_L19P_5	AR29		
5	IO_L09N_5/VREF_5	AM29		
5	IO_L09P_5	AN29		
5	IO_L08N_5	AK29		
5	IO_L08P_5	AL29		
5	IO_L07N_5/VREF_5	AT30		
5	IO_L07P_5	AU30		
5	IO_L06N_5/VRP_5	AP30		
5	IO_L06P_5/VRN_5	AR30		
5	IO_L05_5/No_Pair	AK28		
5	IO_L03N_5/D4	AM30		
5	IO_L03P_5/D5	AN30		
5	IO_L02N_5/D6	AL30		
5	IO_L02P_5/D7	AK30		
5	IO_L01N_5/RDWR_B	AR31		
5	IO_L01P_5/CS_B	AT31		
6	IO_L01P_6/VRN_6	AU33		
6	IO_L01N_6/VRP_6	AT33		
6	IO_L02P_6	AT32		
6	IO_L02N_6	AR32		
6	IO_L03P_6	AN31		
6	IO_L03N_6/VREF_6	AM31		

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
N/A	GND	Y34		
N/A	GND	AU32		
N/A	GND	AN32		
N/A	GND	G32		
N/A	GND	C32		
N/A	GND	AH31		
N/A	GND	AD31		
N/A	GND	T31		
N/A	GND	M31		
N/A	GND	Y30		
N/A	GND	AU28		
N/A	GND	AN28		
N/A	GND	G28		
N/A	GND	C28		
N/A	GND	AT24		
N/A	GND	AN24		
N/A	GND	AJ24		
N/A	GND	AC24		
N/A	GND	AB24		
N/A	GND	AA24		
N/A	GND	Y24		
N/A	GND	W24		
N/A	GND	V24		
N/A	GND	U24		
N/A	GND	L24		
N/A	GND	G24		
N/A	GND	D24		
N/A	GND	AD23		
N/A	GND	AC23		
N/A	GND	AB23		
N/A	GND	AA23		
N/A	GND	Y23		
N/A	GND	W23		
N/A	GND	V23		
N/A	GND	U23		
N/A	GND	T23		
N/A	GND	AD22		
N/A	GND	AU39		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
5	VCCO_5		AH22		
6	VCCO_6		AU38		
6	VCCO_6		AP40		
6	VCCO_6		AL37		
6	VCCO_6		AJ39		
6	VCCO_6		AH29		
6	VCCO_6		AG34		
6	VCCO_6		AG29		
6	VCCO_6		AG28		
6	VCCO_6		AF29		
6	VCCO_6		AF28		
6	VCCO_6		AE40		
6	VCCO_6		AE29		
6	VCCO_6		AE28		
6	VCCO_6		AD29		
6	VCCO_6		AD28		
6	VCCO_6		AC38		
6	VCCO_6		AC35		
6	VCCO_6		AC29		
6	VCCO_6		AC28		
6	VCCO_6		AB29		
6	VCCO_6		AB28		
7	VCCO_7		AA29		
7	VCCO_7		AA28		
7	VCCO_7		Y38		
7	VCCO_7		Y35		
7	VCCO_7		Y29		
7	VCCO_7		Y28		
7	VCCO_7		W29		
7	VCCO_7		W28		
7	VCCO_7		V40		
7	VCCO_7		V29		
7	VCCO_7		V28		
7	VCCO_7		U29		
7	VCCO_7		U28		
7	VCCO_7		T34		

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
3	IO_L67P_3	AU5	
3	IO_L66N_3	AU1	
3	IO_L66P_3	AU2	
3	IO_L65N_3	AJ9	
3	IO_L65P_3	AK8	
3	IO_L64N_3	AU8	
3	IO_L64P_3	AV8	
3	IO_L63N_3/VREF_3	AU7	
3	IO_L63P_3	AV7	
3	IO_L62N_3	AL8	
3	IO_L62P_3	AL9	
3	IO_L61N_3	AU3	
3	IO_L61P_3	AV2	
3	IO_L84N_3	AV6	
3	IO_L84P_3	AW5	
3	IO_L83N_3	AM8	
3	IO_L83P_3	AM9	
3	IO_L82N_3	AV4	
3	IO_L82P_3	AW4	
3	IO_L81N_3/VREF_3	AV3	
3	IO_L81P_3	AW3	
3	IO_L80N_3	AN9	
3	IO_L80P_3	AP8	
3	IO_L79N_3	AW1	
3	IO_L79P_3	AW2	
3	IO_L78N_3	AY7	
3	IO_L78P_3	AY8	
3	IO_L77N_3	AR8	
3	IO_L77P_3	AR9	
3	IO_L76N_3	AW7	
3	IO_L76P_3	AY6	
3	IO_L75N_3/VREF_3	AY3	
3	IO_L75P_3	AY4	
3	IO_L74N_3	AT9	
3	IO_L74P_3	AU9	
3	IO_L73N_3	AY5	
3	IO_L73P_3	BA5	